Materials Declaration

Package	LFCSP
Body Size	9 X 9 mm (7.1mm exposed pad)
LeadCount	64
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	6.44 E-02	274664
Multiaromatic Resin	16.0	1.23 E-02	52317

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	1.24 E-01	528446
Fe	2.35	2.99 E-03	12735
Zn	0.12	1.53 E-04	653
P	0.03	3.80 E-05	162

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	6.24 E-04	2661

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	4.94 E-03	21060

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.17 E-03	9255

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	2.00 E-02	85339

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	2.09 E-03	8901
Resin	21.0	6.26 E-04	2670
Metal Oxide	3.0	8.90 E-05	380
Amine	3.0	8.90 E-05	380
Gamma Butyrolactone	3.0	8.90 E-05	380

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
2.34 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

Materials Declaration

Package	LFCSP
Body Size	9 X 9 mm (7.1mm exposed pad)
LeadCount	64
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	6.44 E-02	274306
Multiaromatic Resin	16.0	1.23 E-02	52248

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	1.24 E-01	527758
Fe	2.35	2.99 E-03	12718
Zn	0.12	1.53 E-04	652
P	0.03	3.80 E-05	162

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.17 E-03	4975

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.00	4.54 E-03	19346
Pb	15.00	8.02 E-04	3416

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.53 E-03	6500

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	2.00 E-02	85228

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	2.09 E-03	8889
Resin	21.0	6.26 E-04	2666
Metal Oxide	3.0	8.90 E-05	379
Amine	3.0	8.90 E-05	379
Gamma Butyrolactone	3.0	8.90 E-05	379

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
2.35 E-01	1000000

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